

1MBI650VXA-170EH-50

IGBT Modules

IGBT MODULE (V series) 1700V / 650A / 1 in one package

■ Features

- High speed switching
- Voltage drive
- Low Inductance module structure

■ Applications

- NPC 3-level Inverter
- Active PFC
- Industrial machines



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at T_c=25°C unless otherwise specified)

Items	Symbols	Conditions	Maximum ratings	Units
Collector-Emitter voltage	V _{CES}		1700	V
Gate-Emitter voltage	V _{GES}		±20	V
Collector current	I _C	Continuous	T _c =25°C 900 T _c =100°C 650	A
	I _C pluse	1ms	1300	
	-I _C		650	
	-I _C pluse	1ms	1300	
	P _C	1 device	4150	
Collector Power Dissipation	P _C	1 device	4150	W
Reverse voltage for FWD	V _R		1700	V
Forword current for FWD	I _F	Continuous	650	A
	I _F pulse	1ms	1300	
Junction temperature	T _j		175	°C
Operating junction temperature (under switching conditions)	T _{jop}		150	
Case temperature	T _C		150	
Storage temperature	T _{slg}		-40 ~ +150	
Isolation voltage	between terminal and copper base (*1)	V _{iso}	AC : 1min.	VAC
	between thermistor and others (*2)			
Screw Torque (*3)	Mounting	M5	6.0	N m
	Main Terminals	M8	10.0	
	Sense Terminals	M4	2.1	

Note *1: All terminals should be connected together during the test.

Note *2: Two thermistor terminals should be connected together, other terminals should be connected together and shorted to base plate during the test.

Note *3: Recommendable Value : Mounting 3.0 ~ 6.0 Nm (M5)
Recommendable Value : Main Terminals 8.0 ~ 10.0 Nm (M8)
Recommendable Value : Sense Terminals 1.8 ~ 2.1 Nm (M4)

● Electrical characteristics (at $T_J = 25^\circ\text{C}$ unless otherwise specified)

Items		Symbols	Conditions		Characteristics			Units	
					min.	typ.	max.		
IGBT+Inverse Diode	Zero gate voltage collector current	I _{CES}	V _{CE} = 1700V V _{GE} = 0V		-	-	4.0	mA	
	Gate-Emitter leakage current	I _{GES}	V _{CE} = 0V V _{GE} =±20V		-	-	800	nA	
	Gate-Emitter threshold voltage	V _{GE(th)}	V _{CE} = 20V I _C = 650mA		6.0	6.5	7.0	V	
	Collector-Emitter saturation voltage	V _{CE(sat)} (terminal) (*4)	I _C = 650A V _{GE} =15V	T _J = 25°C	-	2.10	2.55	V	
				T _J =125°C	-	2.50	-		
				T _J =150°C		2.55	-		
		V _{CE(sat)} (chip)		T _J = 25°C	-	2.00	2.45		
				T _J =125°C	-	2.40	-		
				T _J =150°C		2.45	-		
	Internal gate resistance	R _{G (int)}	-				1.75	-	Ω
	Input capacitance	C _{ies}	V _{CE} =10V, V _{GE} =0V,f=1MHz			-	63	-	nF
	Turn-on time	t _{on}	V _{CC} = 900V I _C = 650A V _{GE} = ±15V			-	1250	-	nsec
		t _r				-	500	-	
		t _{r (l)}				-	150	-	
	Turn-off time	t _{off}	R _G = 1.8 / -2.7 Ω L _S = 70nH			-	1550	-	
		t _t				-	150	-	
	Forward on voltage	V _F (terminal) (*4)	I _F = 650A V _{GE} =0V	T _J = 25°C	-	1.95	2.40	V	
T _J =125°C				-	2.20	-			
T _J =150°C					2.15	-			
V _F (chip)		T _J = 25°C		-	1.85	2.30			
		T _J =125°C		-	2.10	-			
		T _J =150°C			2.05	-			
Reverse recovery time	t _{rr}	I _F = 650A				240	-	nsec	
FWD	Reverse Current	I _R	V _{CE} = 1700V		-	-	3.0	mA	
	Forward on voltage	V _F (terminal) (*4)	I _F = 650A V _{GE} =0V	T _J = 25°C	-	1.95	2.40	V	
				T _J =125°C	-	2.20	-		
				T _J =150°C		2.15	-		
		V _F (chip)		T _J = 25°C	-	1.85	2.30		
				T _J =125°C	-	2.10	-		
		T _J =150°C		2.05	-				
Reverse recovery time	t _{rr}	I _F = 650A			-	240	-	nsec	
Thermistor	Resistance	R	T = 25°C		-	5000	-	Ω	
		T = 100°C		465	495	520			
	B value	B	T = 25/50°C		3305	3375	3450	K	

Note *4: Fuji defined V_{CE} value of terminal by using Sense C1 and Sense C2E1 for Upper arm and Sense C2E1 and Sense E2 for Lower arm.

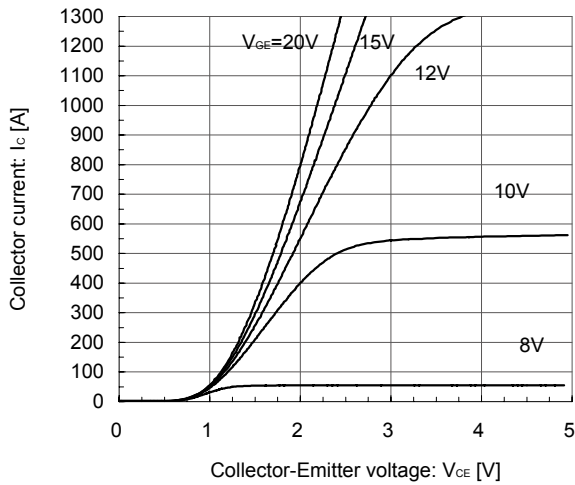
● Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance(1device)	$R_{th(j-c)}$	Inverter IGBT	-	-	0.036	$^\circ\text{C/W}$
		Inverse Diode	-	-	0.072	
		FWD	-	-	0.072	
Contact thermal resistance (1device) (*5)	$R_{th(c-f)}$	with Thermal Compound	-	0.0125	-	

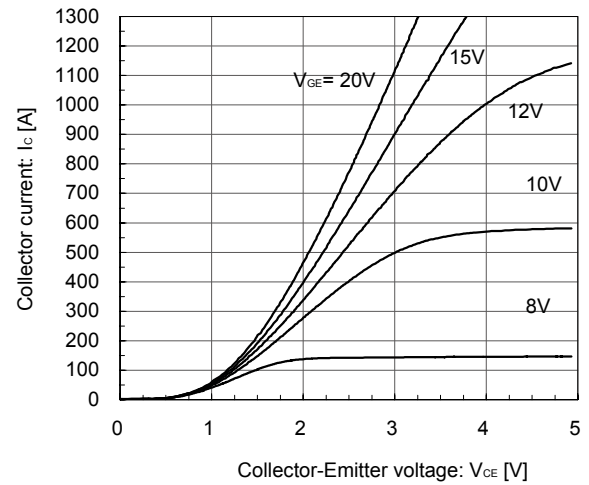
Note *5: This is the value which is defined mounting on the additional cooling fin with thermal compound.

■ Characteristics (Representative)

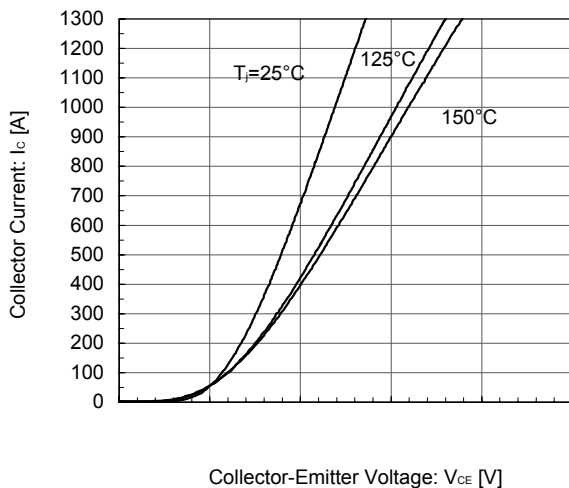
Collector current vs. Collector-Emittor voltage (typ.)
 $T_j = 25^\circ\text{C}$ / chip



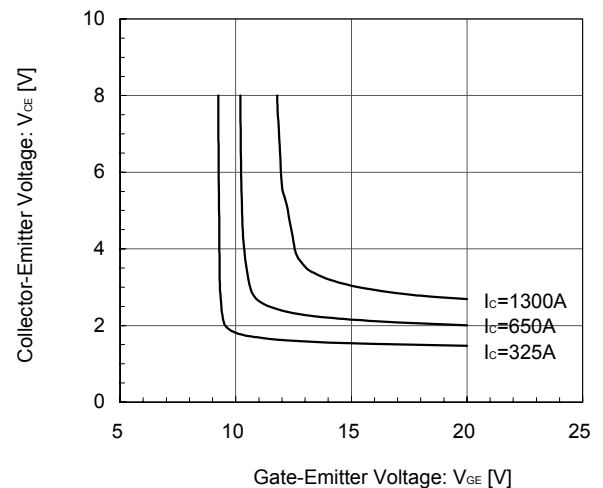
Collector current vs. Collector-Emittor voltage (typ.)
 $T_j = 150^\circ\text{C}$ / chip



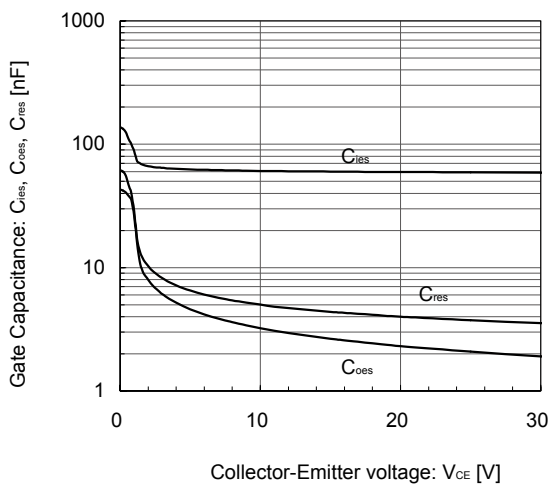
Collector current vs. Collector-Emittor voltage (typ.)
 $V_{GE} = 15\text{V}$ / chip



Collector-Emittor voltage vs. Gate-Emittor voltage (typ.)
 $T_j = 25^\circ\text{C}$ / chip

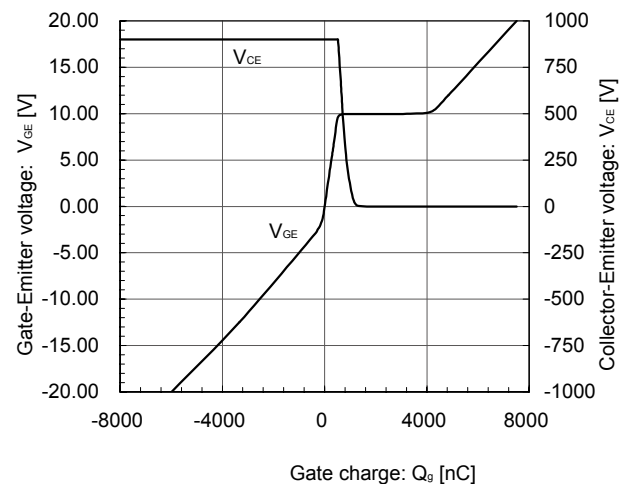


Gate Capacitance vs. Collector-Emittor Voltage (typ.)
 $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$, $T_j = 25^\circ\text{C}$



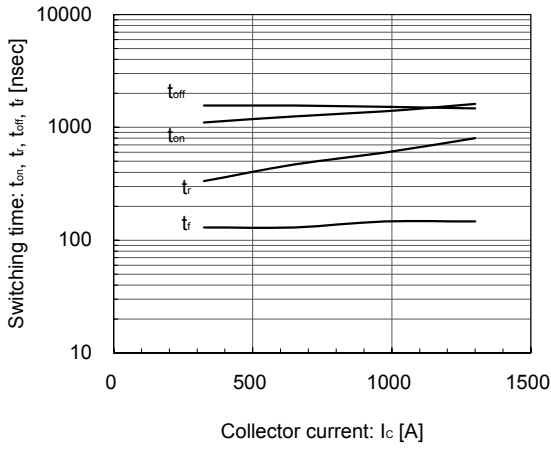
Dynamic Gate Charge (typ.)

$V_{CC} = 900\text{V}$, $I_C = 650\text{A}$, $T_j = 25^\circ\text{C}$



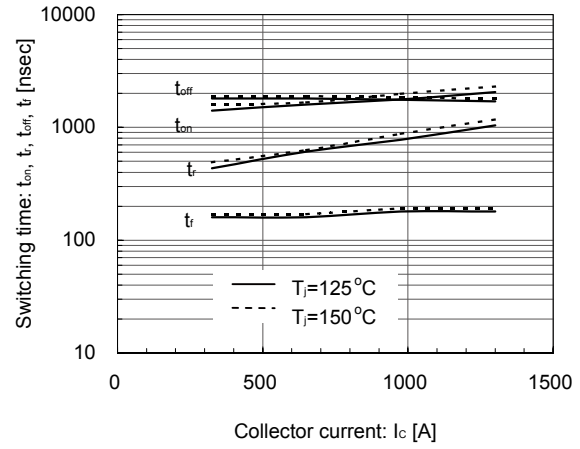
Switching time vs. Collector current (typ.)

$V_{CC}=900V$, $V_{GE}=\pm 15V$, $R_G=+1.8/-2.7\Omega$, $T_J=25^\circ C$



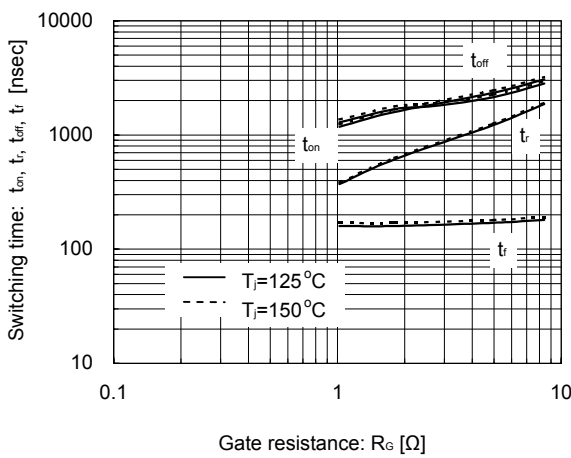
Switching time vs. Collector current (typ.)

$V_{CC}=900V$, $V_{GE}=\pm 15V$, $R_G=+1.8/-2.7\Omega$, $T_J=125^\circ C$, $150^\circ C$



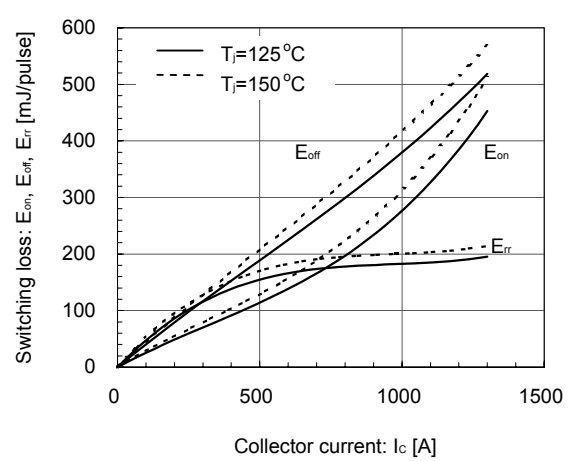
Switching time vs. Gate resistance (typ.)

$V_{CC}=900V$, $I_C=650A$, $V_{GE}=\pm 15V$, $T_J=125^\circ C$, $150^\circ C$



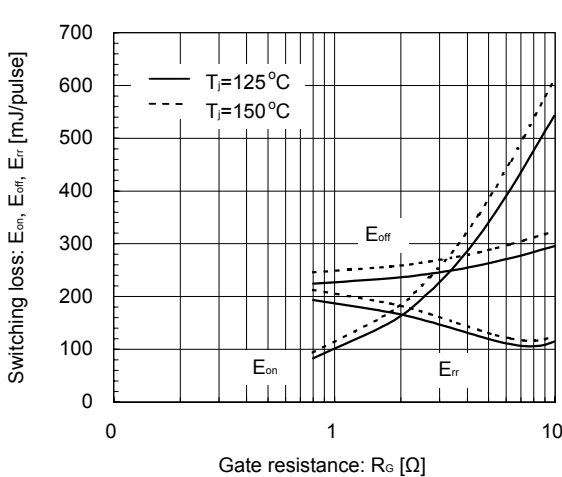
Switching loss vs. Collector current (typ.)

$V_{CC}=900V$, $V_{GE}=\pm 15V$, $R_G=+1.8/-2.7\Omega$, $T_J=125^\circ C$, $150^\circ C$



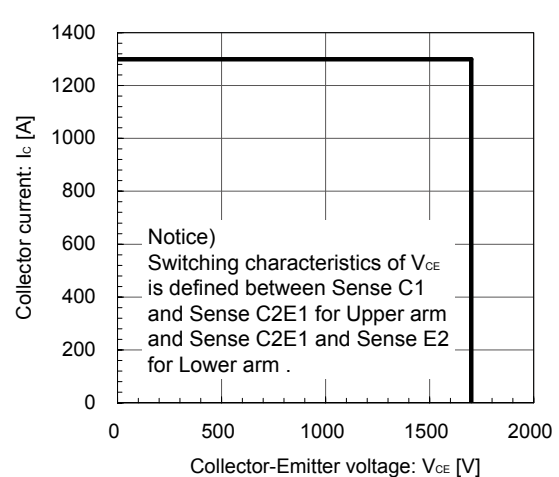
Switching loss vs. Gate resistance (typ.)

$V_{CC}=900V$, $I_C=650A$, $V_{GE}=\pm 15V$, $T_J=125^\circ C$, $150^\circ C$

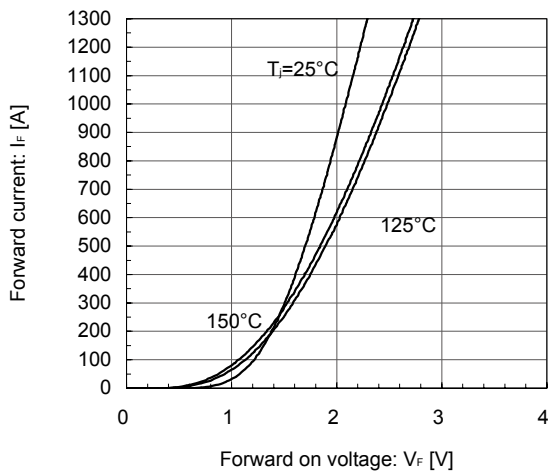


Reverse bias safe operating area (max.)

$+V_{GE}=15V$, $-V_{GE}=15V$, $R_G=+1.8/-2.7\Omega$, $T_J=150^\circ C$

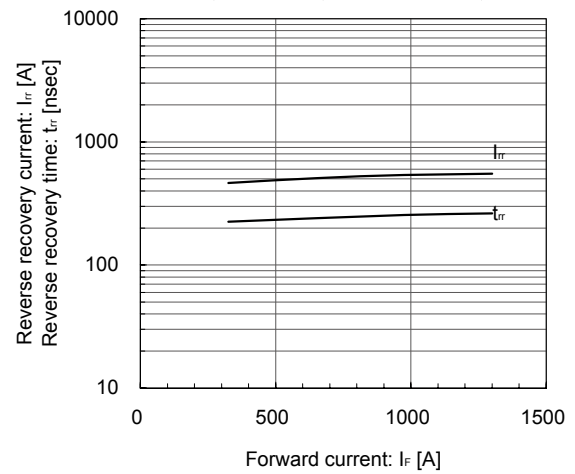


[FWD]

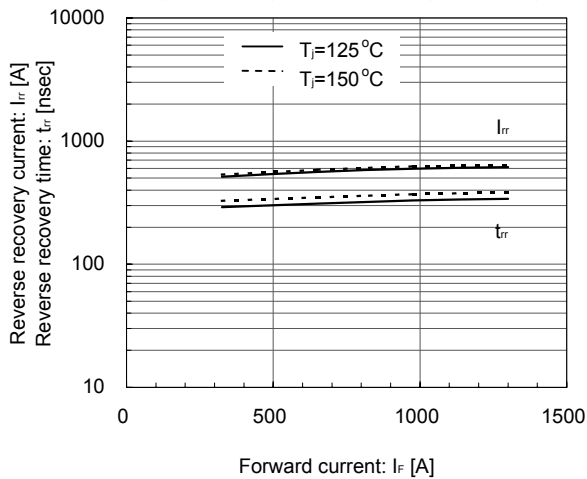
Forward Current vs. Forward Voltage (typ.)
chip

[FWD]

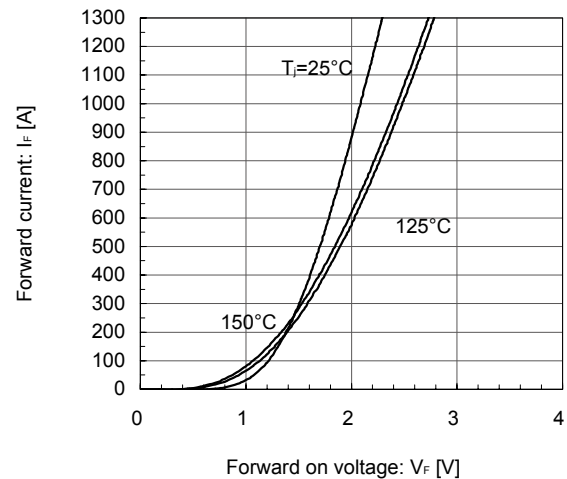
Reverse Recovery Characteristics (typ.)

 $V_{CC}=900V$, $V_{GE}=\pm 15V$, $R_G=+1.8/-2.7\Omega$, $T_J=25^\circ C$ 

Reverse Recovery Characteristics (typ.)

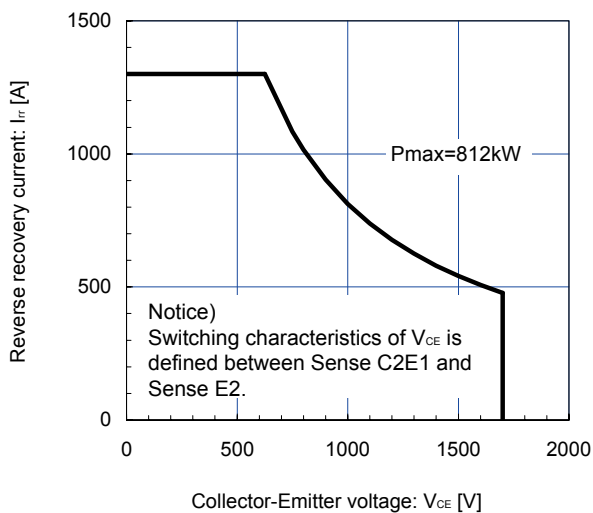
 $V_{CC}=900V$, $V_{GE}=\pm 15V$, $R_G=+1.8/-2.7\Omega$, $T_J=125^\circ C$, $150^\circ C$ 

[Inverse Diode]

Forward Current vs. Forward Voltage (typ.)
chip

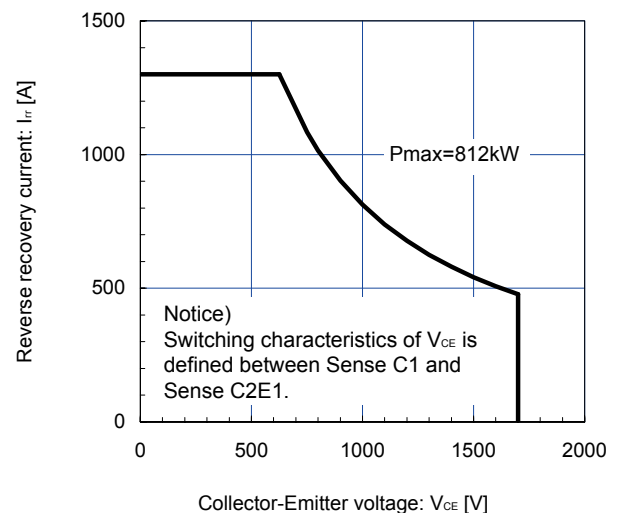
[FWD]

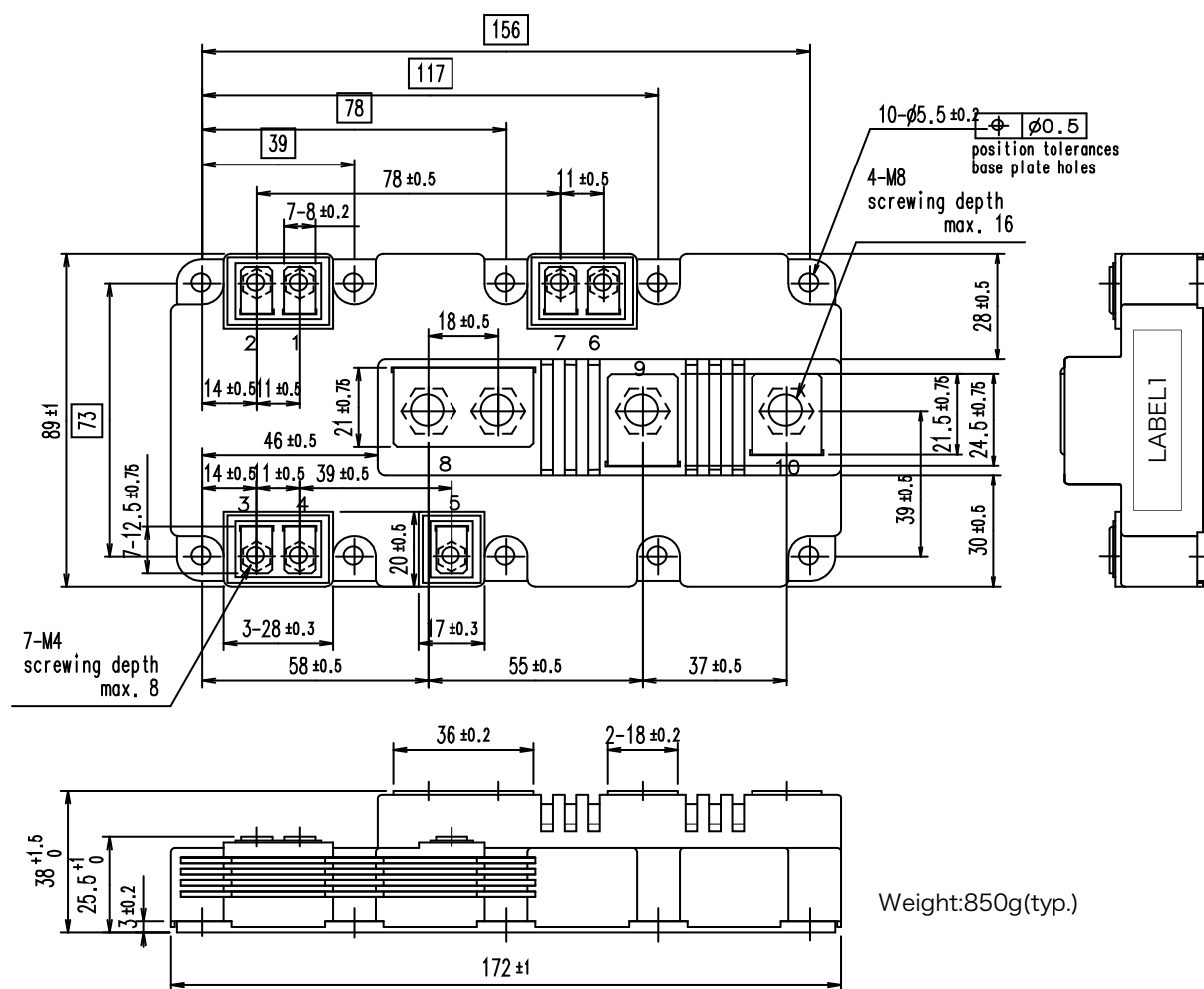
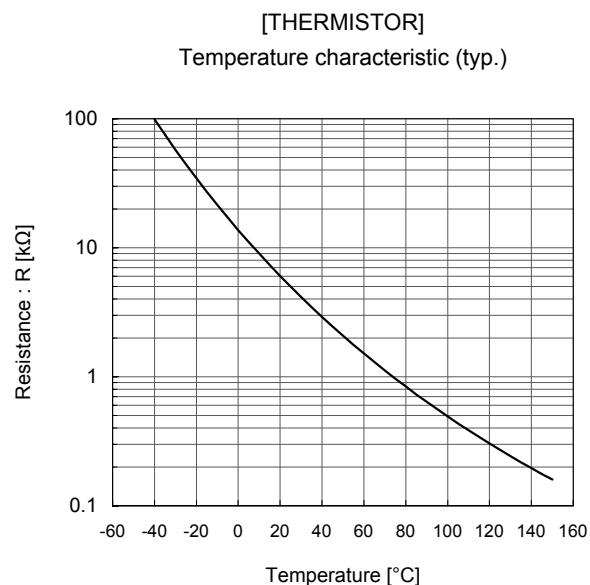
FWD safe operating area (max.)

 $T_J=150^\circ C$ 

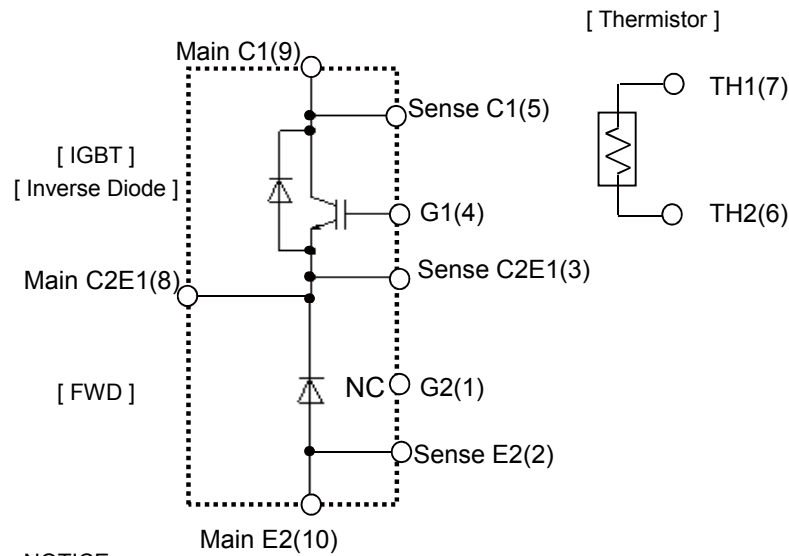
[Inverse Diode]

FWD safe operating area (max.)

 $T_J=150^\circ C$ 



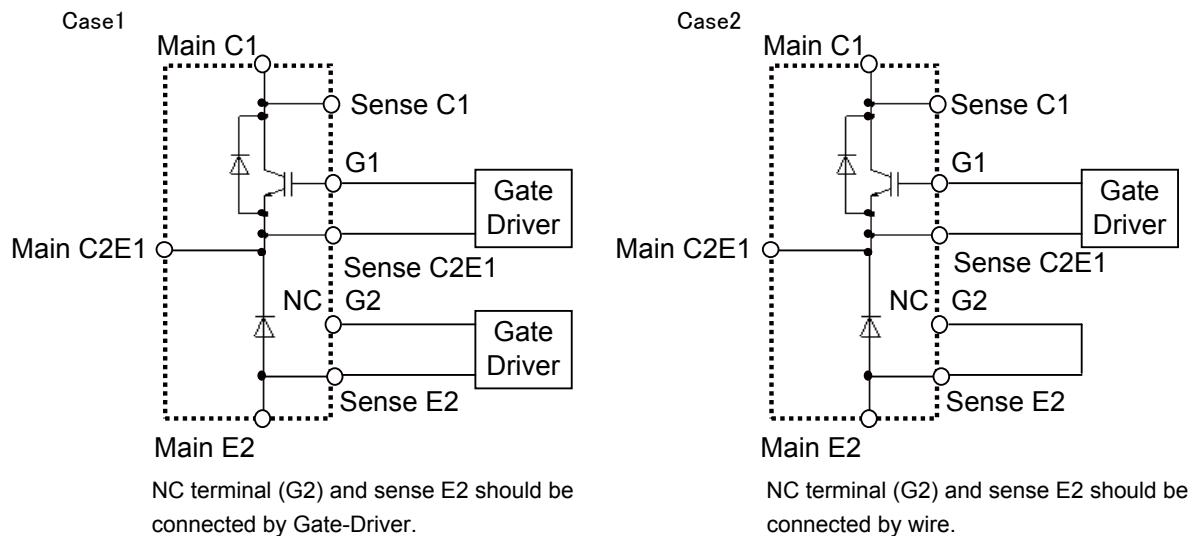
Equivalent Circuit Schematic



NOTICE

There is recommendation of wiring for NC terminal as follows.

Fuji recommends wire connection of CASE1 or CASE2 to fix NC terminal voltage.



WARNING

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			• Industrial robots etc.
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• Emergency equipment for responding to disasters and anti-burglary devices	• Safety devices
• Medical equipment	
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